

Excellent Integrated System Limited

Stocking Distributor

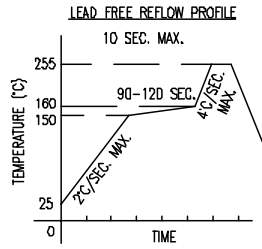
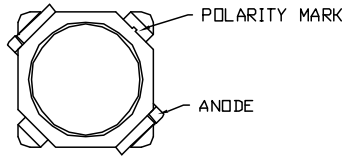
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Lumex, Inc.](#)
[SML-H1505UPGC-TR](#)

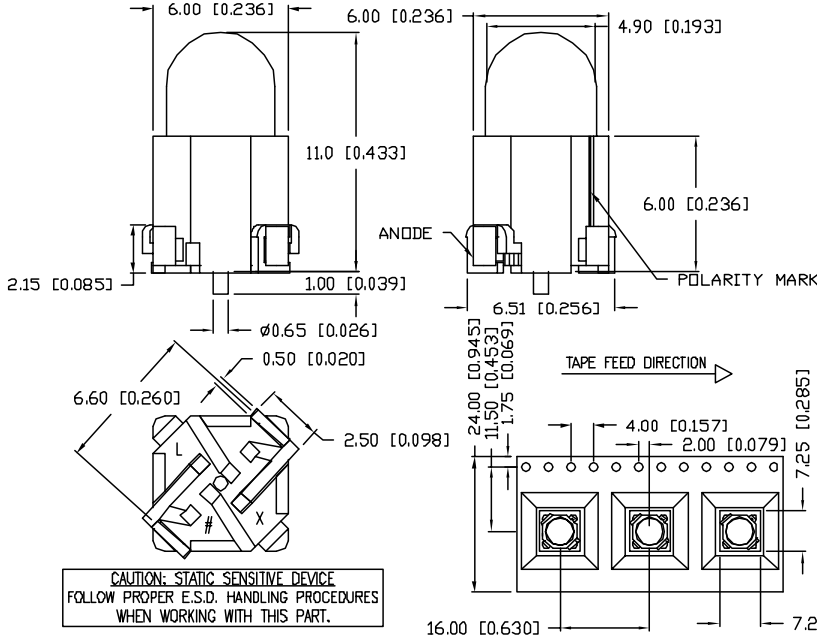
For any questions, you can email us directly:
sales@integrated-circuit.com

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* PATENT PENDING



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.



PART NUMBER
SML-H1505UPGC-TR

REV.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

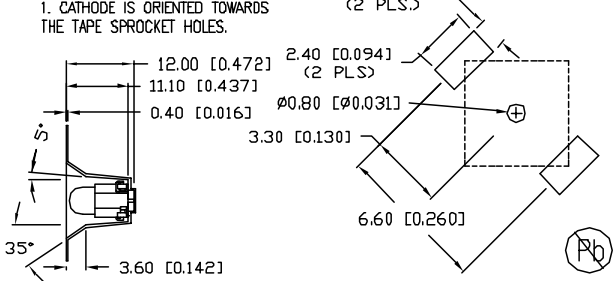
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		520		nm	
FORWARD VOLTAGE		3.3	4.0	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY		7000		mcd	I _f =20mA
VIEWING ANGLE		45		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	20	mA
POWER DISSIPATION	80	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +80	°C
STORAGE TEMP.	-40 TO +100	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		5 SEC. MAX
*T<10μS		

NOTE:
1. CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLES.

RECOMMENDED PAD LAYOUT (2 PLS.)



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION MAX=-DECIMAL PRECISION

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5mm SURFACE MOUNTED DOME LED,
 525nm ULTRA PURE GREEN LED, WATER CLEAR.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JN	CHECKED BY:	APPROVED BY:	DATE: 03.31.08 PAGE: 1 OF 1 SCALE: N/A
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